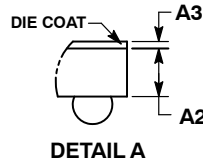
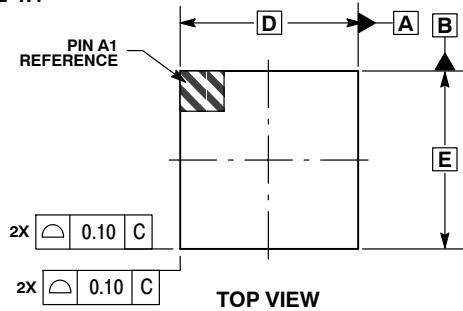




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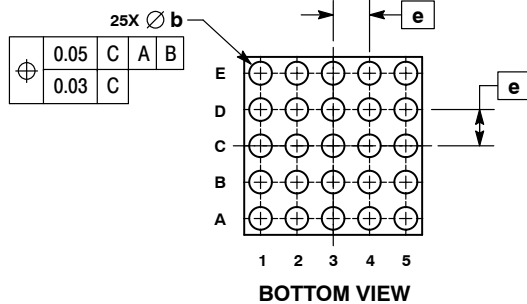
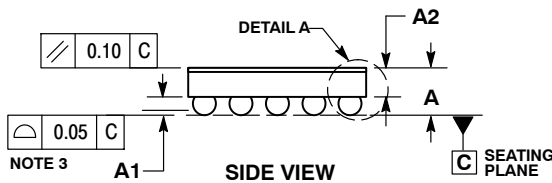
DATE 17 JUL 2012

SCALE 4:1

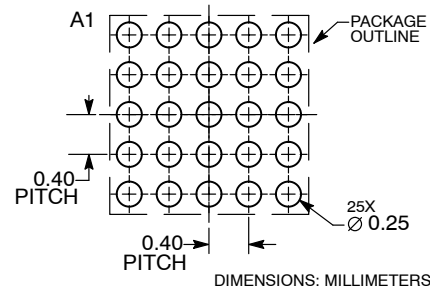


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.60
A1	0.17	0.23
A2	0.36	REF
A3	0.04	REF
b	0.24	0.29
D	2.06	BSC
E	2.06	BSC
e	0.40	BSC



RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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